

Driving decarbonization and digitalization. Together.



Principal Packaging & Process Engineer

Job description

In your new role you will:

- **Proactively participate in the new product roadmap** definitions and cross-examine the development process in order to meet our stretched targets for new product releases, while ensuring manufacture and profitable next generation products in Operations
- **Lead the strategy for long-term process roadmaps** and develop new technologies needed for new and next generation products
- **Collaborate with other R&D functions, Project Management, Operations,** and other stakeholders as the focal person to lead the innovation of assembly and mechanical screening processes for New Product Integration(NPI)
- **Develop and update the design rules that will ensure manufacturability,** including meeting the required process capability and product reliability
- **Identify and mitigate project risks related to backend processes and materials,** through the translation of DFMEA to PFMEA, and using other methods of risk management
- **Resolve development and manufacturing problems with high complexity** involving expert networks, through structured problem-solving techniques like 8D and related tools. Exploits deviations as a tool for discoveries that will support continuous improvement
- **Drive technical decisions** and develop new process technology, including prototype and production tools and equipment for new products
- **Lead the TRB (technical review board)** meetings and collaboration ensuring new product designs are aligned to the core and future core process roadmaps.
- Aside from working with internal manufacturing site, investigate and work with OSATs that will contribute to new product developments. Support supplier quality, purchasing, and other groups to identify and work with material vendors impacting new products and future of supply chain of the business unit

Profile

You are best equipped for this task if you have:

- **Bachelor of Science** (preferred Master's degree) **in engineering, such as mechanical, packaging, chemical, materials, manufacturing, electrical, or electronics engineering**
- **Minimum 10 years in semiconductor or electronic assembly process and/or package engineering;** including hands-on experience package and process development for new products

At a glance

Location:

Job ID: **HRC0740134**

Start date: **Jun 03, 2024**

Entry level: **5+ years**

Type: **Full time**

Contract: **Permanent**

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Job ID: **HRC0740134**
www.infineon.com/jobs



- **Proven ability to define a structured approach in new process research,** development, characterization, qualification, and release to production
- **Deep technical understanding of material, package, and process relationships,** as they contribute to product performance and manufacturing / operation efficiencies
- **Strong knowledge in developing and managing on-site and outsourced back end processes,** such as die attach, wire bond, package sealing, lead, finish, trim and form, and mechanical assemblies
- **Effective team leader and member,** ability to collaborate with other teams and IR-Hi-Rel/Infineon sites for best practice, resource and knowledge sharing, and lead as expert mentoring technicians and new engineers.
- **Strong multi-tasking and prioritization skills,** and effective in defining and meeting ambitious schedules towards project completion
- **Self-starter, fast-learner with experience working in fast-pace and dynamic manufacturing environment**
- Emphasizes personal and professional growth, **keeps current with technical and business knowledge and skills,** maintains a network in field of expertise
- Demonstrated **strong verbal and written communication skills**
- An advantage to have but not required:
 - Proficient in interpretation of mechanical drawings as well as using CAD software
 - Knowledge on military / aerospace industry standards.

#LI-TG1

Benefits

- **Leominster, MA:** Medical, Dental & Vision Plans; Flexible Reimbursement Accounts (FSAs); Industry leading 401k Employer Contribution/Match; Company Performance Bonus; Holiday Pay & Paid Time Off (PTO); Flexible Working Conditions, Part-time Options; Different career paths: Project Management, Technical Ladder, Management & Individual Contributor; Wide range of Training Offers & Career Development Planning; Coaching, Mentoring, Networking Possibilities; International assignments; Basic Life & Dependent Life Insurance; Paid Sick Leave, Accidental Death & Disability Insurance (AD&D) ; Short-term & Long-term Disability ; Employee Assistance Program (EAP) ; Health Promotion Programs ; Reduced Price for Public Transportation

Why Us

Infineon designs, develops, manufactures, and markets a broad range of semiconductors and semiconductor-based solutions, focusing on key markets in the automotive, industrial, and consumer sectors. Its products range from standard components to special components for digital, analog, and mixed-signal applications to customer-specific solutions together with the appropriate software.

We are on a journey to create the best Infineon for everyone.

This means we embrace diversity and inclusion and welcome everyone for who they are. At Infineon, we offer a working environment characterized by trust, openness, respect and tolerance and are committed to give all applicants and employees equal opportunities. We base our recruiting decisions on the applicant's experience and skills.

We look forward to receiving your resume, even if you do not entirely meet all the requirements of the job posting.

Please let your recruiter know if they need to pay special attention to something in order to enable your participation in the interview process.

[Click here](#) for more information about Diversity & Inclusion at Infineon.



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IR HiRel Products Inc., is an equal opportunity employer. All qualified applicants will receive consideration for employment without regard to race, color, religion, sex (including pregnancy, childbirth, or related medical conditions), gender identity, national origin, ancestry, citizenship, age, physical or mental disability, legally protected medical condition, family care status, military or veteran status, marital status, domestic partner status, sexual orientation, or any other basis protected by local, state, or federal laws.

Employment at Infineon is contingent upon proof of your legal right to work in the United States under applicable law, verification of satisfactory references and successful completion of a background check and drug test, and signing all your onboarding documents.

In some instances, if applicable, U.S. export control laws require that Infineon obtain a U.S. government export license prior to releasing technologies to certain persons. This offer is contingent upon Infineon's ability to satisfy these export control laws as related to your employment and anticipated job activities. The decision whether or not to submit and/or pursue an export license to satisfy this contingency, if applicable, shall be at Infineon's sole discretion.

Infineon Technologies takes data privacy and identity theft very seriously. As such, we do not request personally-identifiable information (PII) from applicants over the internet or electronically. Please kindly refrain from disclosing your PII electronically during the application process or to unauthorized websites that may purport to be Infineon or any of our affiliates.

This position requires access to documentation that is controlled by the export laws of the United States. Candidates are required to provide proof of either US citizenship, Permanent US residency or classification as a protected individual as defined in 8USC 1324b(a)(3).

